

Features

- Lead free as standard (RoHS compliant*)
- Protects 1 line or 1 I/O port
- Bidirectional configuration
- ESD protection >40 kV
- Low capacitance ~3 pF typical
- Replaces 0805 MLV devices

CDSOD323-TxxC - TVS Diode Array Series

General Information

The markets of portable communications, computing and video equipment are challenging the semiconductor industry to develop increasingly smaller electronic components.

Bourns offers Transient Voltage Suppressor Array diodes for surge and ESD protection applications, in SOD323 package size format. The Transient Voltage Supressor Array series offers a choice of voltage types ranging from 3 V to 24 V in a unidirectional or bidirectional configuration. Bourns® Chip Diodes conform to JEDEC standards, are easy to handle on standard pick and place equipment and their flat configuration minimizes roll away.

The Bourns® device will meet IEC 61000-4-2 (ESD), IEC 61000-4-4 (EFT) and IEC 61000-4-5 (Surge) requirements.

UNIDIRECTIONAL BIDIRECTIONAL

Applications

Digital cameras

PDAs and notebooks

MP3 players and GPS
USB interface

Cell phones

Electrical & Thermal Characteristics	(@ T 25 °C Unloss Other	wice Noted)
Electrical & Thermal Characteristics	$(@ IA = 25 \ C Onless Other$	wise Noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power (t _p = 8/20 µs)	P _{PP}	350	W
Operating Temperature	TJ	-55 °C to 150 °C	°C
Storage Temperature	T _{STG}	-55 ℃ to 150 ℃	°C

		CDSOD323-								
Parameter	Symbol	Uni- T03	Bi- T03C	Uni- T05	Bi- T05C	Uni- T08	Bi- T08C	Uni- T12	Bi- T12C	Unit
Min. Breakdown Voltage @ 1 mA	VBR	4.0	4.0	6.0	6.0	8.5	8.5	13.3	13.3	V
Working Peak Voltage	Vwм	3.3	3.3	5.0	5.0	8.0	8.0	12.0	12.0	V
Maximum Clamping Voltage @ Ip = 1 A	VF	7.0	7.0	9.8	9.8	13.4	13.4	19.0	19.0	V
Maximum Clamping Voltage @ 8/20 µs @ IPP	Vc	19.0 V @ 20 A	19.0 V @ 20 A	18.3 V @ 17 A	18.3 V @ 17 A	18.5 V @ 17 A	18.5 V @ 17 A	28.3 V @ 11 A	28.3 V @ 11 A	V
Maximum Leakage Current @ V _{WM}	lo	5	5	5	5	2	2	1	1	μA
Typical Capacitance @ 0 V, 1 MHz	CJ				:	3				pF

Notes:

1. Part numbers with suffix "C" indicate bidirectional device, i.e. CDSOD323-T05C.

2. For bidirectional devices only, the electrical specifications apply in both directions.

* RoHS Directive 2002/95/EC Jan 27 2003 including Annex

Specifications are subject to change without notice. Customers should verify actual device performance in their specific applications.

CDSOD323-TxxC - TVS Diode Array Series

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Electrical & Thermal Characteristics (@ T_A = 25 °C Unless Otherwise Noted)

		CDSOD323-						
Parameter	Symbol	Uni- T15	Bi- T15C	Uni- T18	Bi- T18C	Uni- T24	Bi- T24C	Unit
Min. Breakdown Voltage @ 1 mA	VBR	16.7	16.7	20.0	20.0	26.7	26.7	V
Working Peak Voltage	Vwm	15.0	15.0	18.0	18.0	24.0	24.0	V
Maximum Clamping Voltage @ Ip = 1 A	VF	24.0	24.0	29.0	29.0	43.0	43.0	V
Maximum Clamping Voltage @ 8/20 μs @ Ιρρ	Vc	31.8 V @ 10 A	31.8 V @ 10 A	45.0 V @ 8 A	45.0 V @ 8 A	56.0 V @ 6 A	56.0 V @ 6 A	V
Maximum Leakage Current @ V _{WM}	lo	1				μA		
Typical Capacitance @ 0 V, 1 MHz	С			3	3			pF

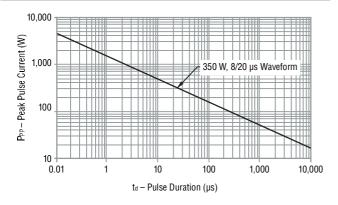
Notes:

1. Part numbers with suffix "C" indicate bidirectional device, i.e. CDSOD323-T05C.

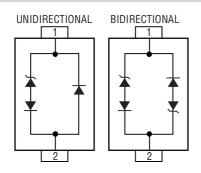
2. For bidirectional devices only, the electrical specifications apply in both directions.

Performance Graphs

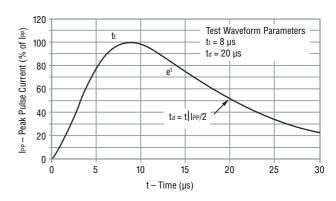
Peak Pulse Power vs Pulse Time



Block Diagram



Pulse Wave Form



How To Order

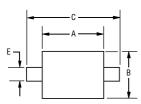
	CD SOD323 -	T 05 C
Common Code		
Package — • SOD323 = SOD-323 Package		
Model T = Transient Voltage Supressor		┘││
Working Peak Reverse Voltage		
Suffix		

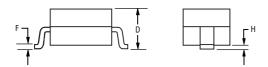
C = Bidirectional Diode

CDSOD323-TxxC - TVS Diode Array Series

Product Dimensions

This is a molded JEDEC SOD-323 package with lead free 100 % Sn plating on the terminations. It weighs approximately 30 mg and has a flammability rating of UL 94V-0.

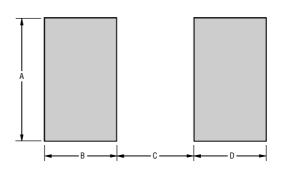




Dimensions			
А	0.60 - 1.90 0.063 - 0.075		
В	<u>1.15 - 1.45</u> 0.045 - 0.057		
С	<u>2.39 - 2.70</u> 0.094 - 0.106		
D	0.92 - 1.10 0.036 - 0.043		
E	0.25 - 0.40 0.010 - 0.016		
F	0.10 - 0.20 0.004 - 0.008		
н	<u>0.10</u> 0.004 MAX.		

DIMENSIONS = MILLIMETERS (INCHES)

Recommended Footprint



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Dimensions (Nominal)			
А	<u>0.80</u> 0.031		
В	<u>0.80</u> 0.031		
С	<u>1.40</u> 0.055		
D	<u>0.80</u> 0.031		

DIMENSIONS = MILLIMETERS (INCHES)

Typical Part Marking

Each device has device marking outlined below and the unidirectional devices have an additional Polarity Band indicating the cathode.

CDSOD323-T03	3
CDSOD323-T03C	3C
CDSOD323-T05	5
CDSOD323-T05C	5C
CDSOD323-T08	8
CDSOD323-T08C	8C
CDSOD323-T12	2
CDSOD323-T12C	2C
CDSOD323-T15	6
CDSOD323-T15C	6C
CDSOD323-T18	1
CDSOD323-T18C	1C
CDSOD323-T24	
CDSOD323-T24C	4C

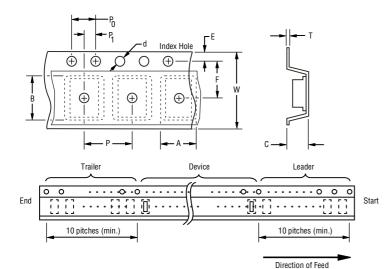
Specifications are subject to change without notice. Customers should verify actual device performance in their specific applications.

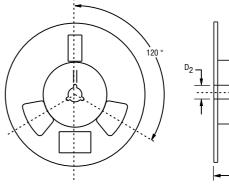
CDSOD323-TxxC - TVS Diode Array Series

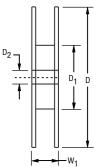
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Packaging Information

The surface mount product is packaged in an 8 mm x 4 mm tape and reel format per EIA-481 standard.







Item	Symbol	SOD-323
Carrier Width	А	<u>1.55 ±0.10</u> (0.061 - 0.004)
		(0.061 - 0.004) 2.90 ±0.10
Carrier Length	В	(0.114 - 0.004)
Carrier Depth	С	$\frac{1.35 \pm 0.10}{(0.053 - 0.004)}$
Sprocket Hole	d	<u>1.55 ±0.05</u> (0.061 - 0.002)
Reel Outside Diameter	D	<u>178</u> (7.008)
Reel Inner Diameter	D ₁	80.0 (3.150) Min.
Feed Hole Diameter	D ₂	<u>13.0 ±0.20</u> (0.512 - 0.008)
Sprocket Hole Position	E	<u>1.75 ±0.10</u> (0.069 - 0.004)
Punch Hole Position	F	<u>3.50 ±0.05</u> (0.138 - 0.002)
Punch Hole Pitch	Р	$\frac{4.00 \pm 0.10}{(0.157 - 0.004)}$
Sprocket Hole Pitch	P ₀	$\frac{4.00 \pm 0.10}{(0.157 - 0.004)}$
Embossment Center	P1	<u>2.00 ±0.05</u> (0.079 - 0.002)
Overall Tape Thickness	Т	<u>0.20 ±0.10</u> (0.008 - 0.004)
Tape Width	W	8.00 ±0.20 (0.315 - 0.008)
Reel Width	W ₁	13.5 (0.531) Max.
Quantity per Reel		3,000



Reliable Electronic Solutions

Asia-Pacific: Tel: +886-2 2562-4117 • Fax: +886-2 2562-4116 Europe: Tel: +41-41 768 5555 • Fax: +41-41 768 5510 The Americas: Tel: +1-951 781-5500 • Fax: +1-951 781-5700 www.bourns.com

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